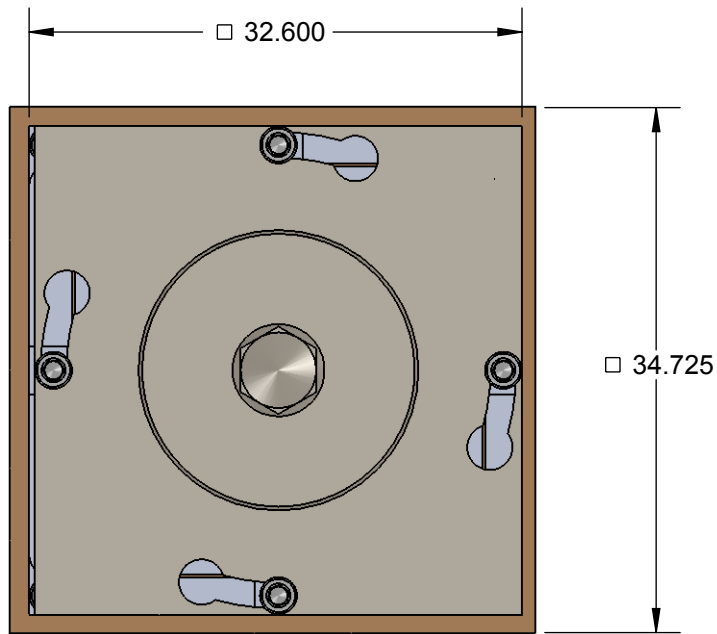


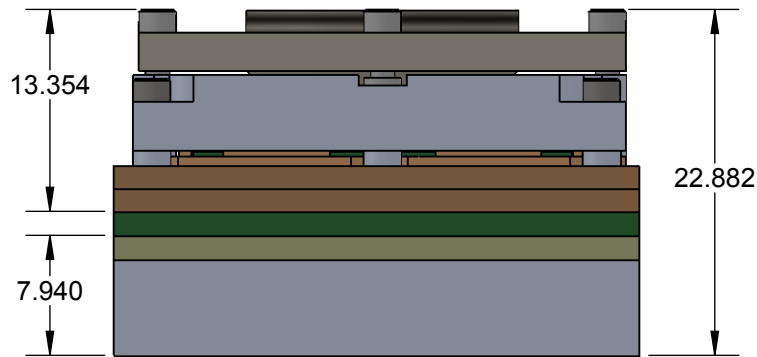
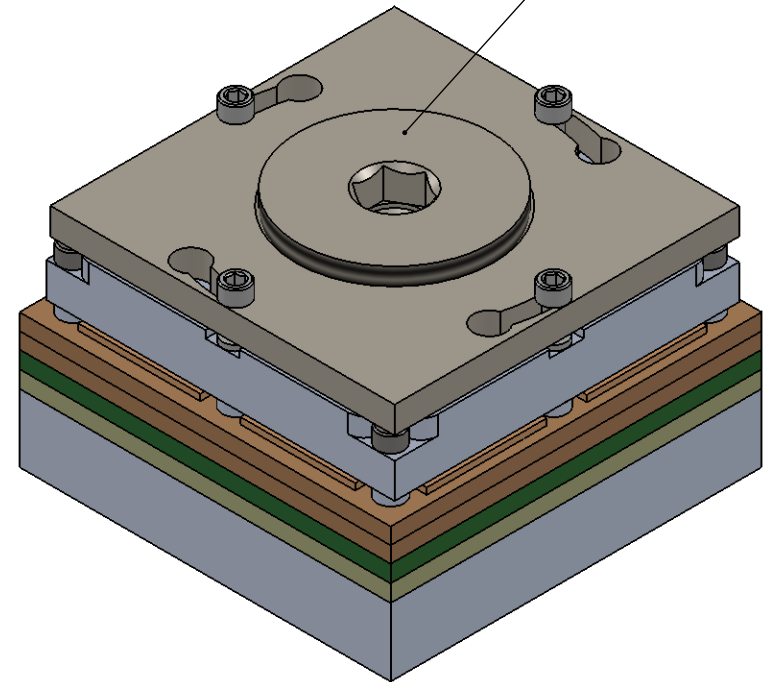
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS



FEATURES:

- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time


Torque until hard stop is met (floating guide bottoms out)



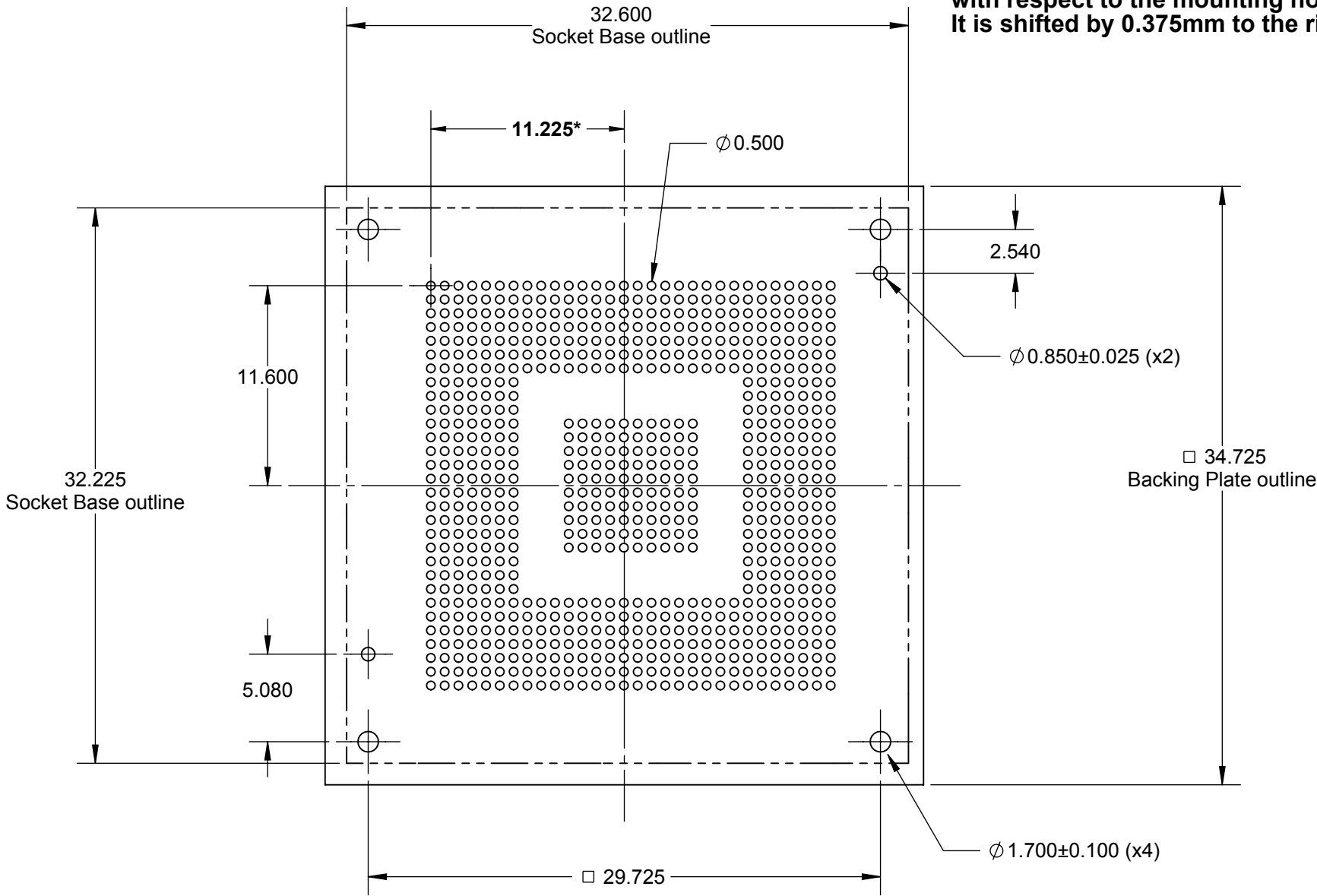
Description: SBT-BGA Socket

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.


 SBT-BGA-6527 Drawing ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 51.18	STATUS: Released ENG: M.A. Fedde FILE: SBT-BGA-6527 Dwg	SHEET: 1 OF 4 DRAWN BY: M. Raske DATE: 05/27/2015	REV. A SCALE: 2:1

***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is shifted by 0.375mm to the right of center.**

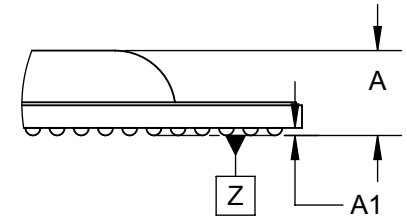
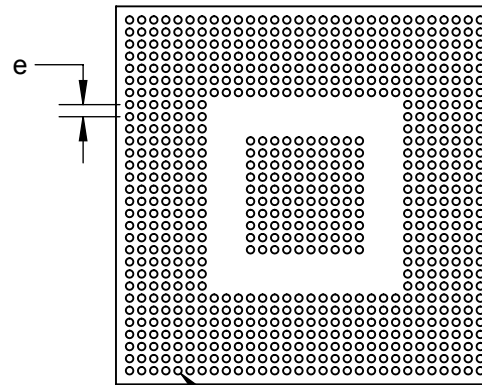
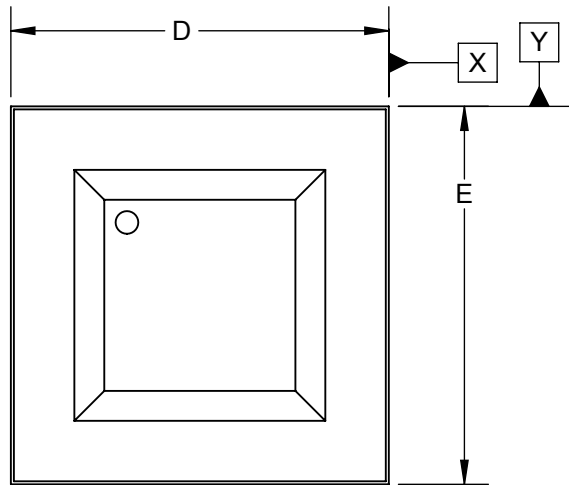


Description: Recommended PCB Layout

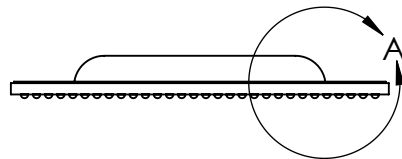
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>SBT-BGA-6527 Drawing ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Material: N/A Finish: N/A Weight: 51.18	STATUS: Released ENG: M.A. Fedde FILE: SBT-BGA-6527 Dwg	SHEET: 2 OF 4 DRAWN BY: M. Raske DATE: 05/27/2015	REV. A SCALE: 3:1

Ironwood Package Code BGA774B



DETAIL A
SCALE 4 : 1



ϕb	$\phi 0.10$	\textcircled{S}	Z
	$\phi 0.25$	\textcircled{S}	Z X \textcircled{S} Y \textcircled{S}


DIM	Minimum	Maximum
A	2.308	2.808
A1	0.36	0.46
b		0.50
D	25.00 BSC	
E	25.00 BSC	
e	0.80 BSC	
ARRAY	30x30	
PIN COUNT	744	

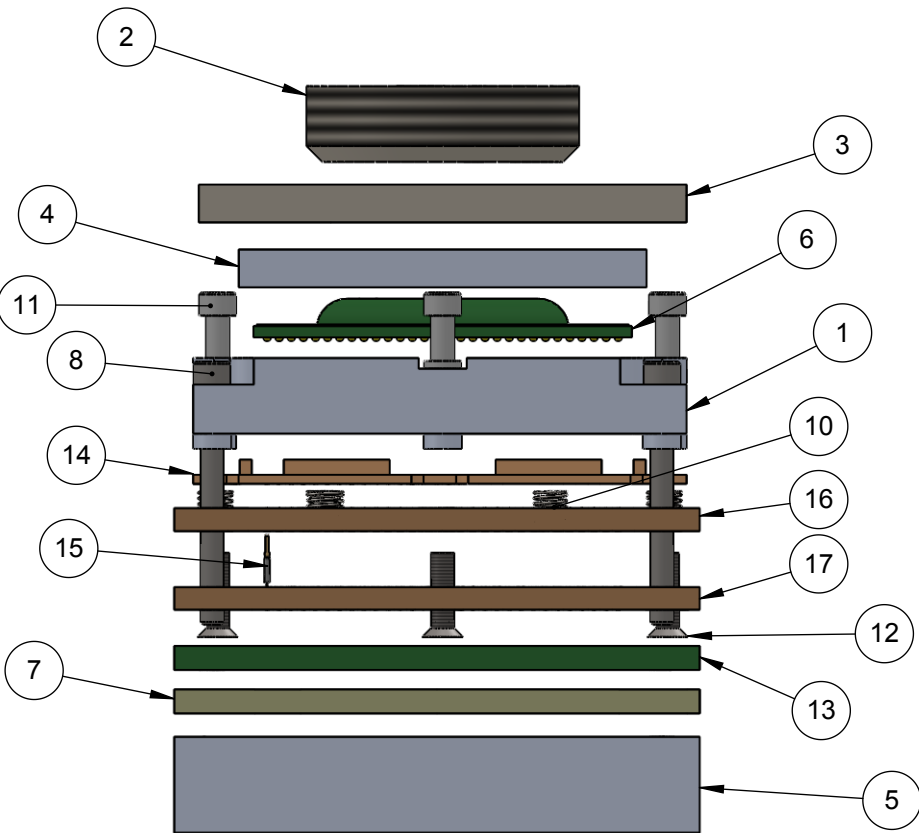
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible BGA

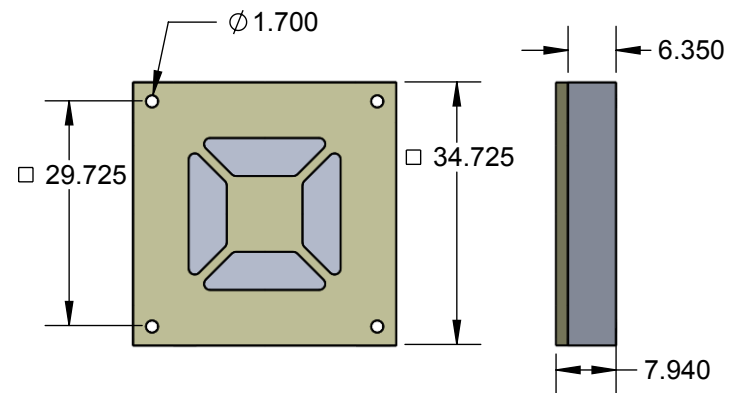
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6527 Drawing ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 51.18	STATUS: Released ENG: M.A. Fedde FILE: SBT-BGA-6527 Dwg	SHEET: 3 OF 4 DRAWN BY: M. Raske DATE: 05/27/2015	REV. A SCALE: 2:1



ITEM NO.	Description	Material
1	Socket Base SBT 27x27mm Ni plated 0.375mm shift	7075-T6 Aluminum Alloy
2	Compression Screw, M18	7075-T6 Aluminum Alloy
3	Socket Lid, 32.225 X 32.225	7075-T6 Aluminum Alloy
4	Compression Plate, 26.95 X 26.95	7075-T6 Aluminum Alloy
5	SBT Ni plt backing plt 27mm IC	7075-T6 Aluminum Alloy
6	Test Chip	Material <not specified>
7	Insulation Plate 27mm IC	FR4
8	#0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
9	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel
10	Floating Guide Spring	Alloy Steel (SS)
11	#0-80 Shoulder Screw, 1.59mm thread length	Stainless Steel (303)
12	#0-80, 90 deg., head pin guide screw, Peek material 5.5715mm overall Length	PEEK unfilled
13	Test PCB	Material <not specified>
14	Floating Guide, BGA744, 0.8mm pitch, Size: 32.60mm x 32.225mm	Semitron MDS 100
15	SBT Pin, SBT-BGA 0.5mm-0.8mm	
16	Middle Guide: BGA744, 0.8mm pitch Size: 34.725mm x 34.725mm	Semitron MDS 100
17	Bottom Guide BGA744, 0.8mm pitch	Semitron MDS 100




Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

**PIN DETAIL
Scale 16:1**

Backing and Insulation Plate

 SBT-BGA-6527 Drawing ©2015 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 51.18	STATUS: Released	SHEET: 4 OF 4	REV. A
		ENG: M.A. Fedde	DRAWN BY: M. Raske	SCALE: 2:1
		FILE: SBT-BGA-6527 Dwg	DATE: 05/27/2015	